Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Title - Representative Phone - Representative* Phone - Representative* Phone - Representative* Phone - Representative* Product-Env-Stewards Product-En	PC SOCIATION CONNECTING ECTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2025-06-06 Contact Name Title - Contact* Phone - Contact* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-	2-21.1											als and Mf	g Informat	ion	
Second S	pplier Informa	ntion								,			<u> </u>		
Title - Contact Name Product Enviro Compliance NA Product Enviro Stewards @onsemi.com Product Enviro Compliance NA Product Enviro Stewards @onsemi.com NA Nanufacturing Site Weight* UOM Ur Nanufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy NS SOT23 GP XSTR SPCL TR Nanufacturing Proccess Body Temperature Nanufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed Natte Tin (Sn) -	Company name*			Company un	Company unique ID			Unique ID Authority				Response Date*			
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Reflow Cycles Requester Item Number Reflow Cycles Requester Item Number Requeste	ntact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Ur SBC807-40LT3G SS SOT23 GP XSTR SPCL TR 2025-06-06 CN1 8.02 mg Ea Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 Seconds 3	oduct-Env-Steward	ds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*			
SBC807-40LT3G SS SOT23 GP XSTR SPCL TR 2025-06-06 CN1 8.02 mg Ea Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles	Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester 1	Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Veight*	UOM	Unit Type
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Comments				·		8 I D-020 MSI	L Kaung			T *				ber of Reflow Cyc	ies
	•	(SII) - annealed	C	U Alloy	1			200		JC	30	second	18 3		
ver 1 - maximum time at peak temperature during soldering is 10-30 seconds		no of nook townous t	duulna s-1:	domina ia 10-1	20 saconda										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and the remaining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	eous Material Weight Unit of Meas		Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Lead Frame	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond	0.01	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0099	mg